



Understanding Solar Module Test Failures: Key Takeaways from Kiwa PVEL's PV Module Reliability Scorecard

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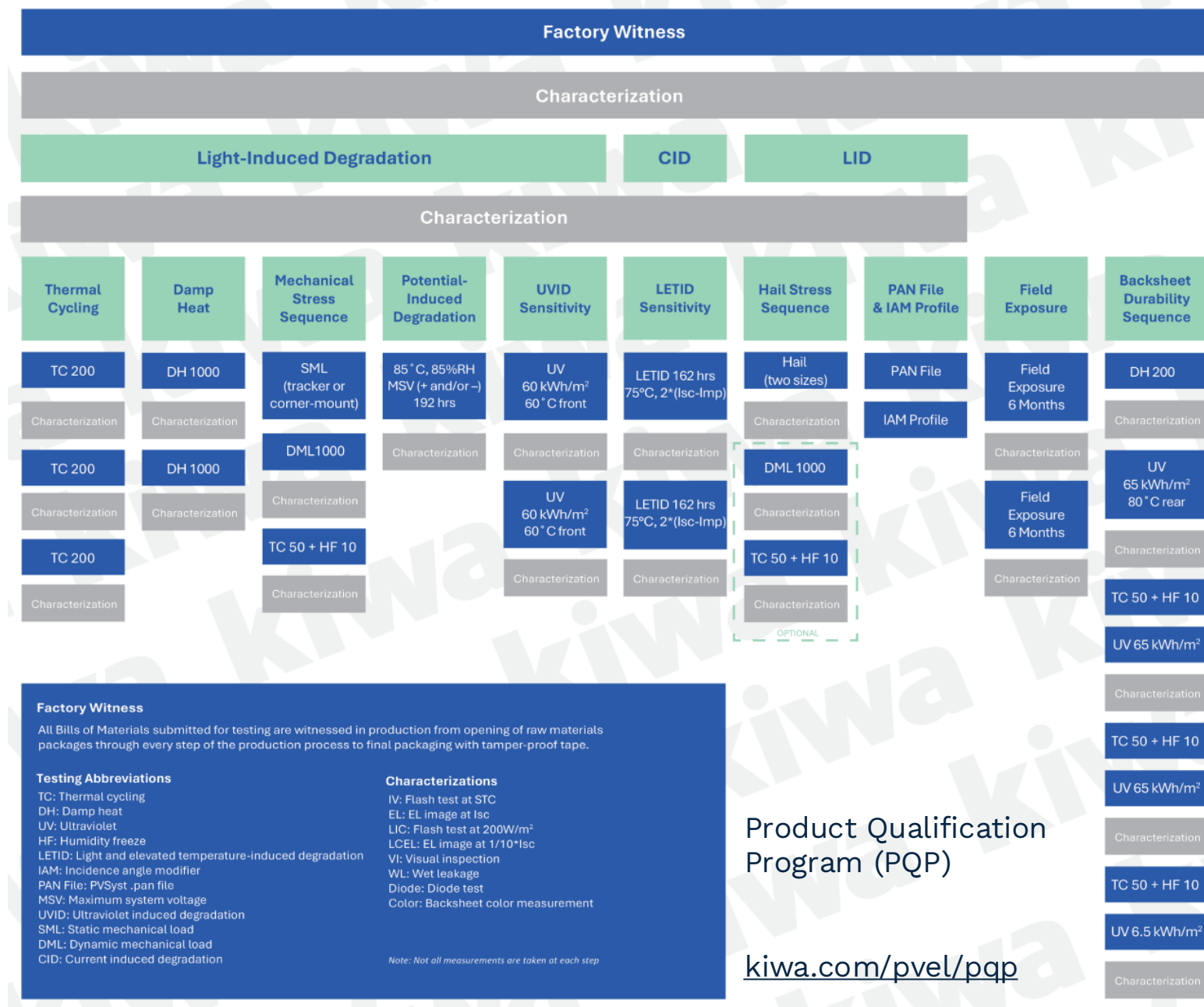
June 9-13, 2025

kiwa

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Kiwa PVEL' PQP

- Independent lab for PV Module **Performance and Reliability Testing.**
- PQP evolves every two years based on feedback from downstream partners, module manufacturers, and the industry's collective understanding of module failure modes and test mechanisms.
- Test stress levels defined in PQP are beyond IEC.



PV Module Reliability Scorecard

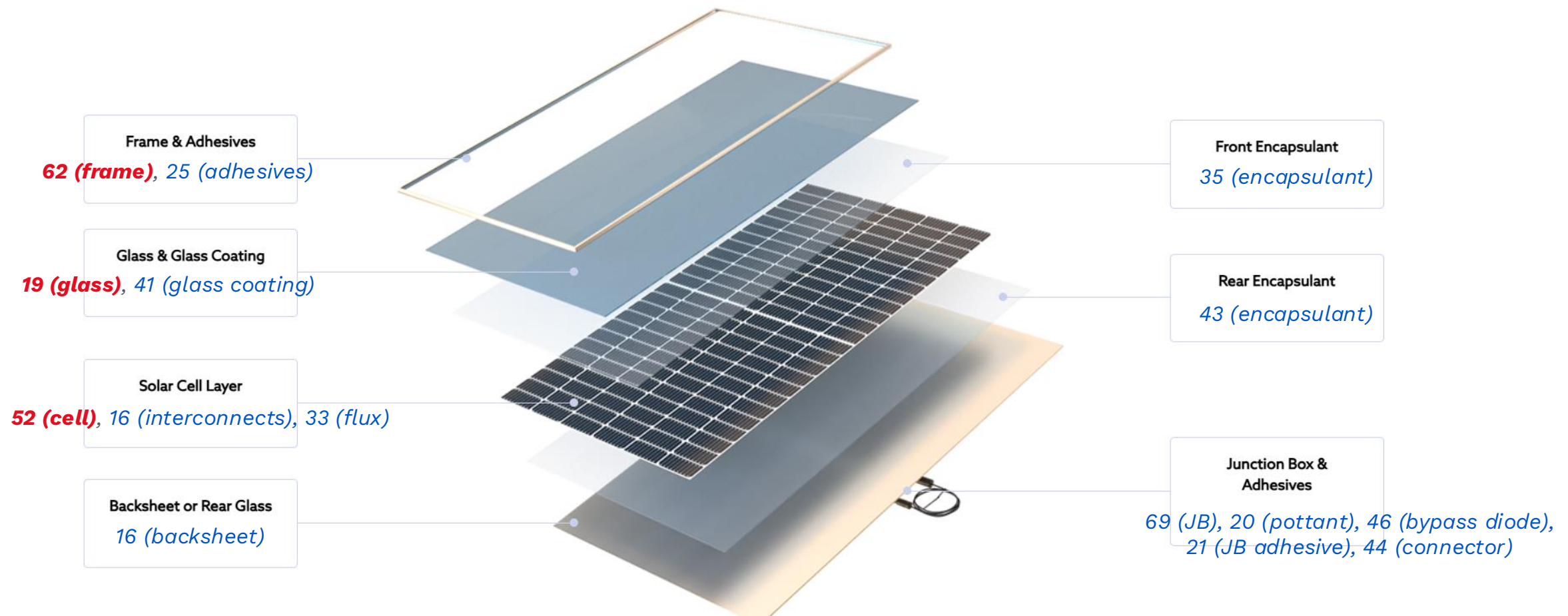
- Releases every year.
 - 11th edition released on June 4, 2025.
- Showcased a broad range of **Top Performer** manufacturers and module model types for their superior test results.



Visit at www.scorecard.pvel.com



Bill of Materials (BOM)



***Manufacturers,** Model types

‘Top Performer’ Status Criteria

- Top Performers are listed for **seven PQP test** categories.
 - Modules must **NOT** have experienced
 - a wet leakage failure
 - a ‘major’ defect during visual inspection
 - a diode failure during that particular test
 - TC, DH, MSS and PID must have **< 2% power degradation**.
 - HSS must not have experienced glass breakage during hail testing using **40 mm hail or larger**.
 - LID + LETID must have **< 1% power degradation** when combining the LID and LETID test results.
 - PAN performance must place in the **top quartile** for energy yield in Kiwa PVEL’s PVsyst simulations.
- To be eligible for the 2025 Scorecard, manufacturers must have
 - Completed the PQP sample production **factory witness after Oct 1, 2023**.
 - Submitted at least two factory-witnessed PV module samples to all PQP reliability tests.

Top Performer Search Tool SnapShot

Cell Technology

☐ Select All

☐ p-type PERC

☐ n-type TOPCon

☐ n-type HJT

☐ n-type xBC

		MANUFACTURER	MODEL TYPE								MODULE DESIGN	CELL
Manufacturer Name	+		JKMxxxN-66HL4M-BDV	✓	✓	↓	40	✓	✓		bifacial - 2.0 glass//2.0 glass	n-ty
PQP Test	+		JKMxxxN-72HL4-BDX	✓	✓	↓	55	✓	✓		bifacial - 2.5 glass//2.5 glass	n-ty
Module Design	+		ZXM7-UHLDD120-xxx/N	✓	✓	↓	40	✓	✓		bifacial - 2.0 glass//2.0 glass	n-ty
Cell Technology	+		ZXM7-UHLDD132-xxx/N	✓	✓	↓	40	✓	✓		bifacial - 2.0 glass//2.0 glass	n-ty
Power Class Range	+		ZXM7-UHLDD144-xxx/N	✓	✓	↓	40	✓	✓	✓	bifacial - 2.0 glass//2.0 glass	n-ty
Wafer Size (mm)	+		ZXM7-UHLDD144-xxx/N	✓	✓	↓	40	✓	✓	✓	bifacial - 2.0 glass//2.0 glass	n-ty
Factory Location	+		SRP-xxx-BTC-BG	✓	✓	↓	40	✓	✓		bifacial - 2.0 glass//2.0 glass	n-ty

Key Takeaways

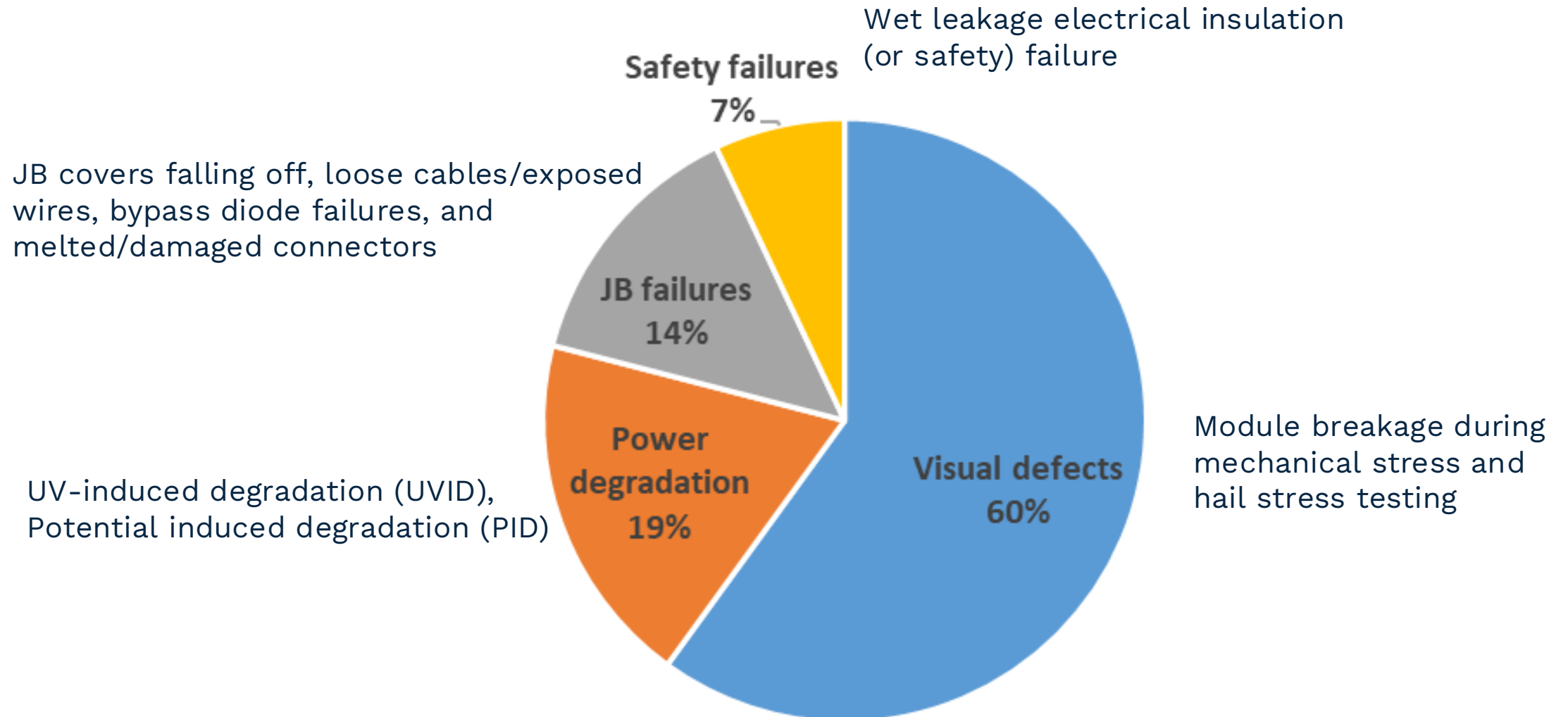
50 manufacturers included in the 2025 Scorecard as Top Performers. Nine of them have at least one model type listed as a Top Performer in each of the seven tests.

Only 21 module models achieved Top Performer status in all reliability tests (TC, DH, MSS, HSS, PID and LID+LETID). Of those, only three were Top Performers in those tests plus PAN performance.

PID and PAN results improved and MSS, HSS and LID+LETID power loss continues to be minimal. But TC and DH have worsened, and the module breakage rate for MSS and HSS has increased. UVID remains a source of concern for some BOMs, but has improved for others.

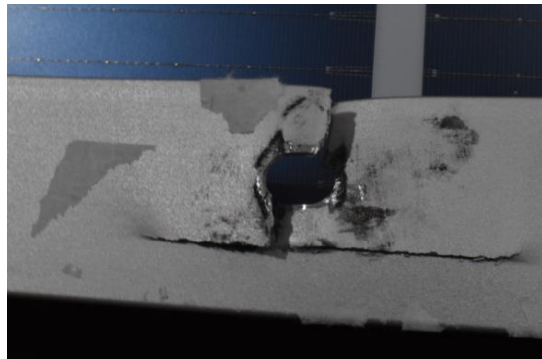
83% of module manufacturers and 59% of BOMs had at least one test failure, up from the 66% and 41% reported in the 2024 Scorecard, respectively.

PQP Failures Statistics

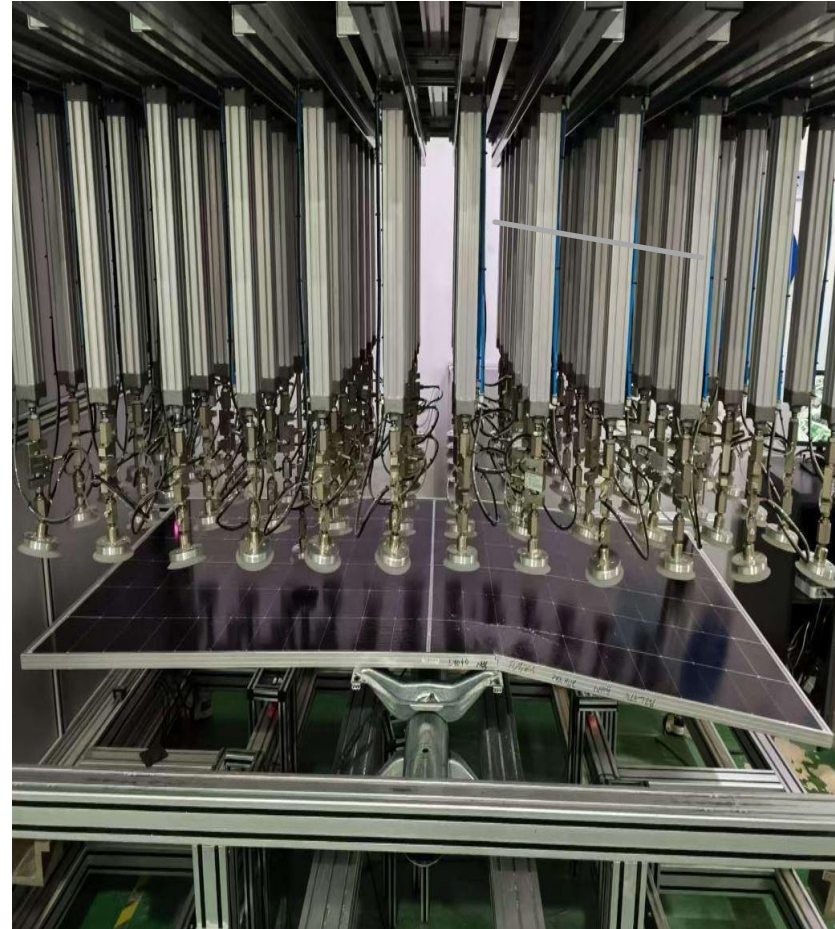


Failure Spotlights: Major Visual Defects

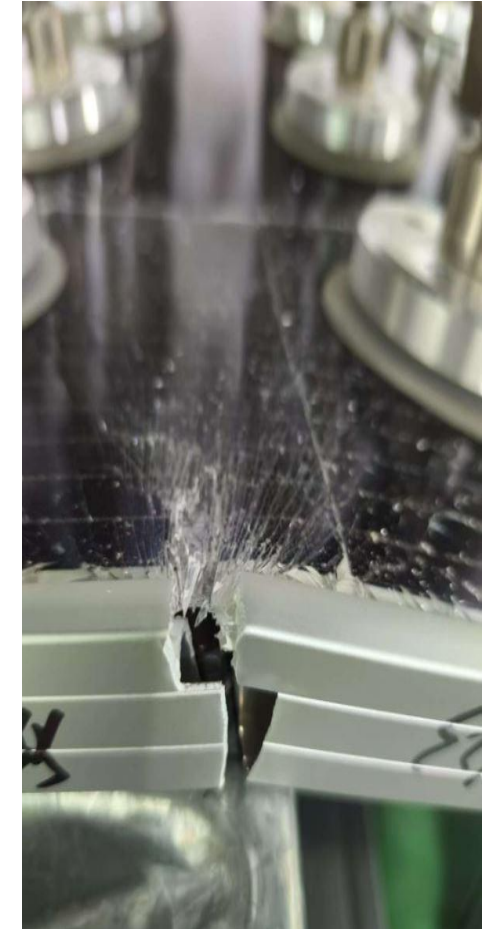
- Visual inspections identify issues that cause premature field failure.
- Major defects (delamination, corrosion, broken or cracked surfaces, etc.) as per IEC 61215 and IEC 61730 criteria.
- 20% of BOMs experienced one or more failures in MSS, increased from just 7% in the 2023 and 2024 Scorecards. **Most of these failures were due to glass breakage and/or frame damage,**



Frame deformation

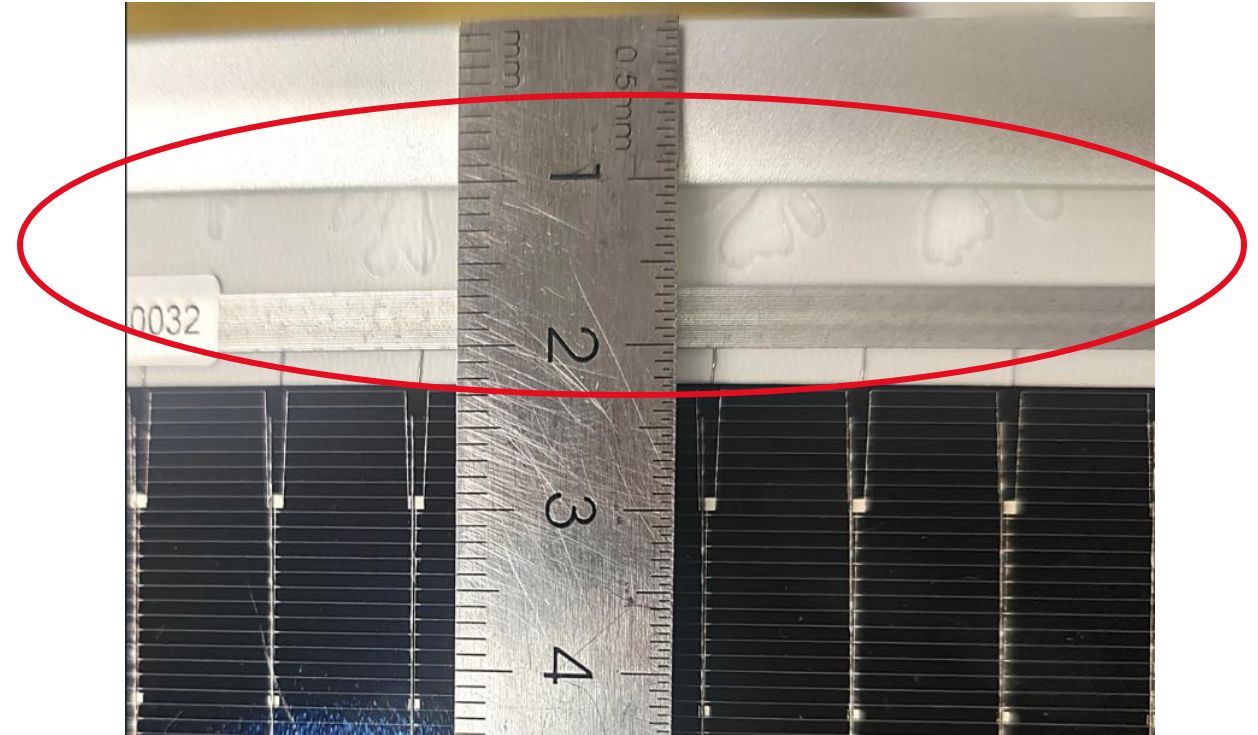


Module frame and glass broke during DML testing, after being weakened during SML.



Failure Spotlights: Major Visual Defects

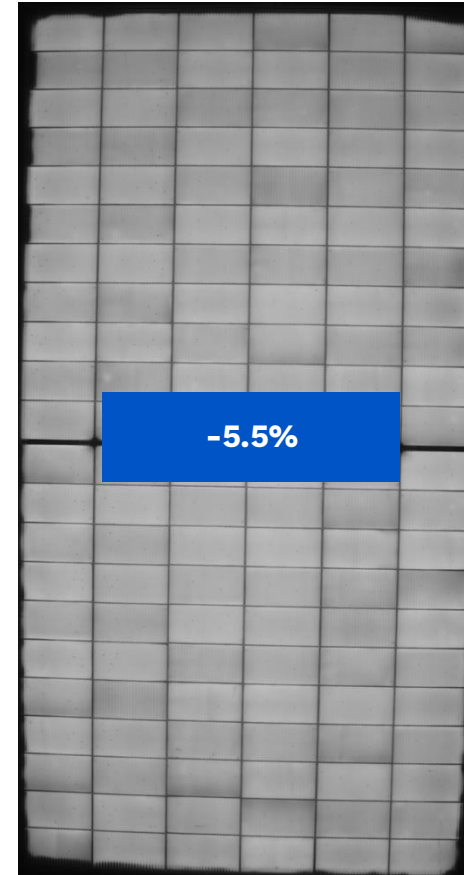
- Visual inspections identify issues that cause premature field failure.
- Major defects (delamination, corrosion, broken or cracked surfaces, etc.) as per IEC 61215 and IEC 61730 criteria.
- 20% of BOMs experienced one or more failures in MSS, increased from just 7% in the 2023 and 2024 Scorecards. **Most of these failures were due to glass breakage and/or frame damage,**
- Bubbles formation causing delamination following TC and/or DH testing. They create a safety risk by forming a potential **electrical path from the module's current-carrying parts to the grounded frame.**



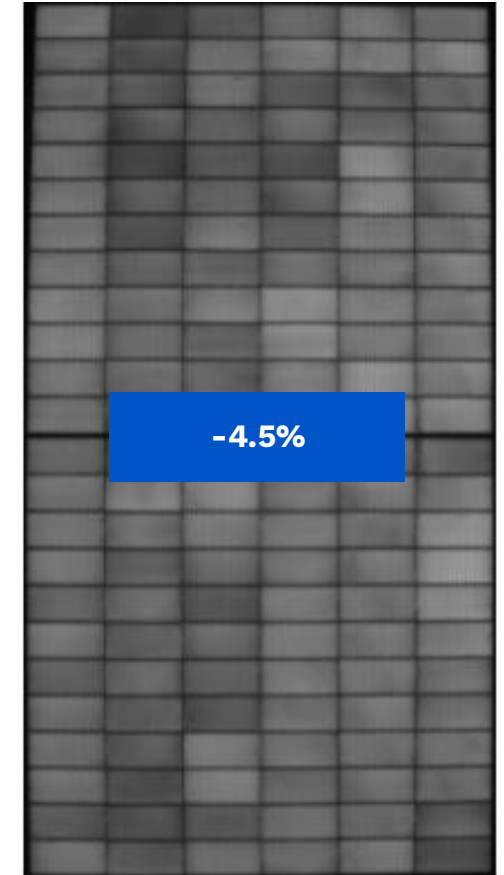
Bubbles can be seen between the frame and the ribbon (major defect)

Failure Spotlights: Power Degradation

- Modules with power degradation failures may underperform in the field.
- PQP does not assign specific pass/fail thresholds for degradation, manufacturers may initiate a retest if power loss exceeds their or their customers' expectations.
 - Accounted BOMs that undergo a **retest due to power loss**.
- HJT module degraded 5.5% in DH2000 testing, triggering a retest request by the manufacturer. Linked to **potential corrosion** due to moisture entering G/G laminate along the perimeter and through JB holes.
- TOPCon module degraded to 4.5% following 120 kWh/m² of UV exposure (UVID testing). Likely attributed to **cell passivation loss**.



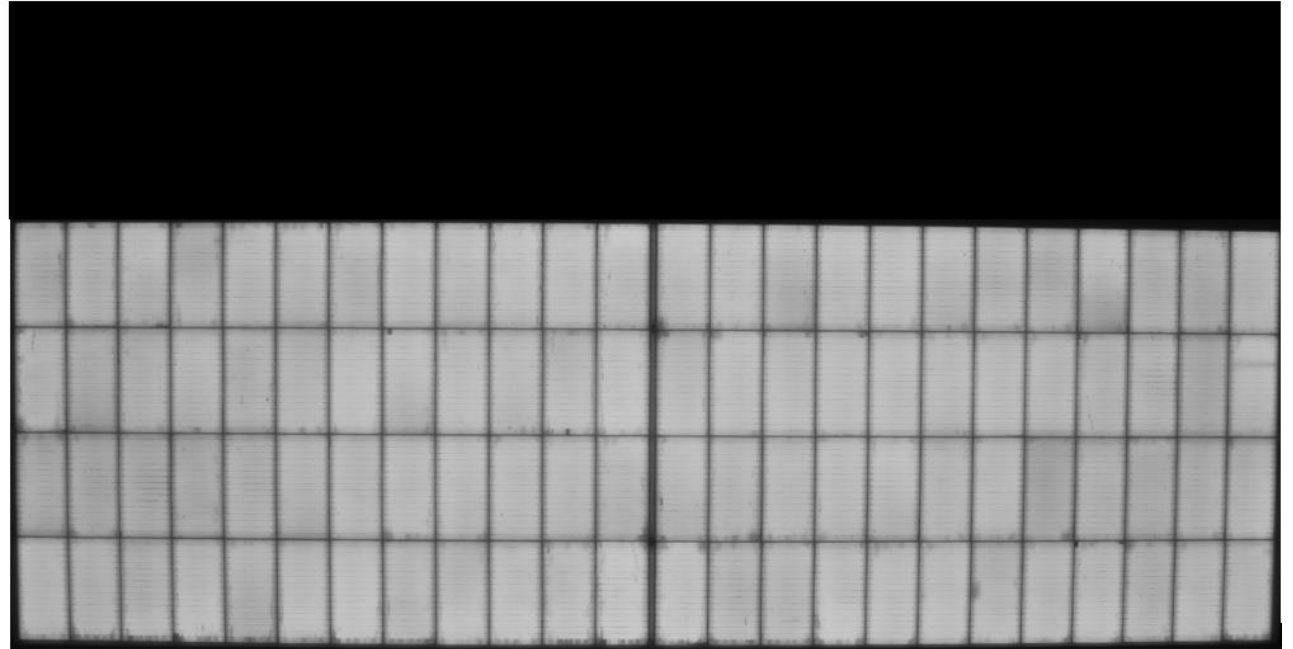
DH2000



UVID120

Failure Spotlights: Junction Box Failure

- Functionality of the module's bypass diodes evaluated after TC and MSS testing.
 - Accounted BOMs with non-functioning diodes in reverse and/or forward bias.
- Following TC600, this module had a **short-circuited bypass diode**, resulting in **33% power loss**.
 - This BOM passed the IEC duration TC200, but experienced catastrophic power loss following TC600.
- Two manufacturers had failing bypass diode.



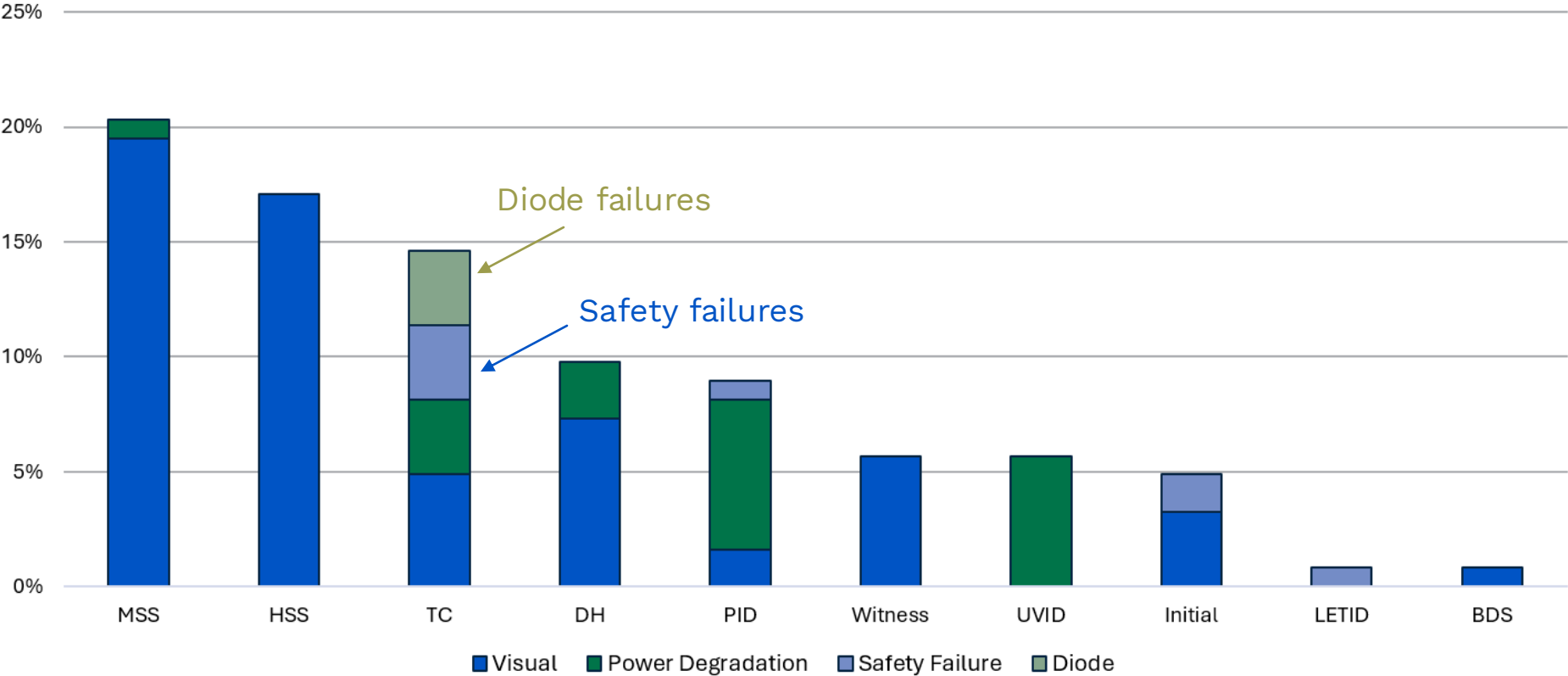
Failure Spotlights: Safety Failures

- Modules with safety failures may be hazardous to operate in the field.
- Module safe operation is determined via **wet leakage testing** using the IEC 61215 standard.
- This module failed wet leakage testing following TC200, meaning that it failed an IEC 61215 certification test.
 - **Improper curing of the pottant** inside the junction box, leading to exposed electrical circuitry.
- Detected at least seven BOMs from different manufacturers.



PQP Failure Statistics

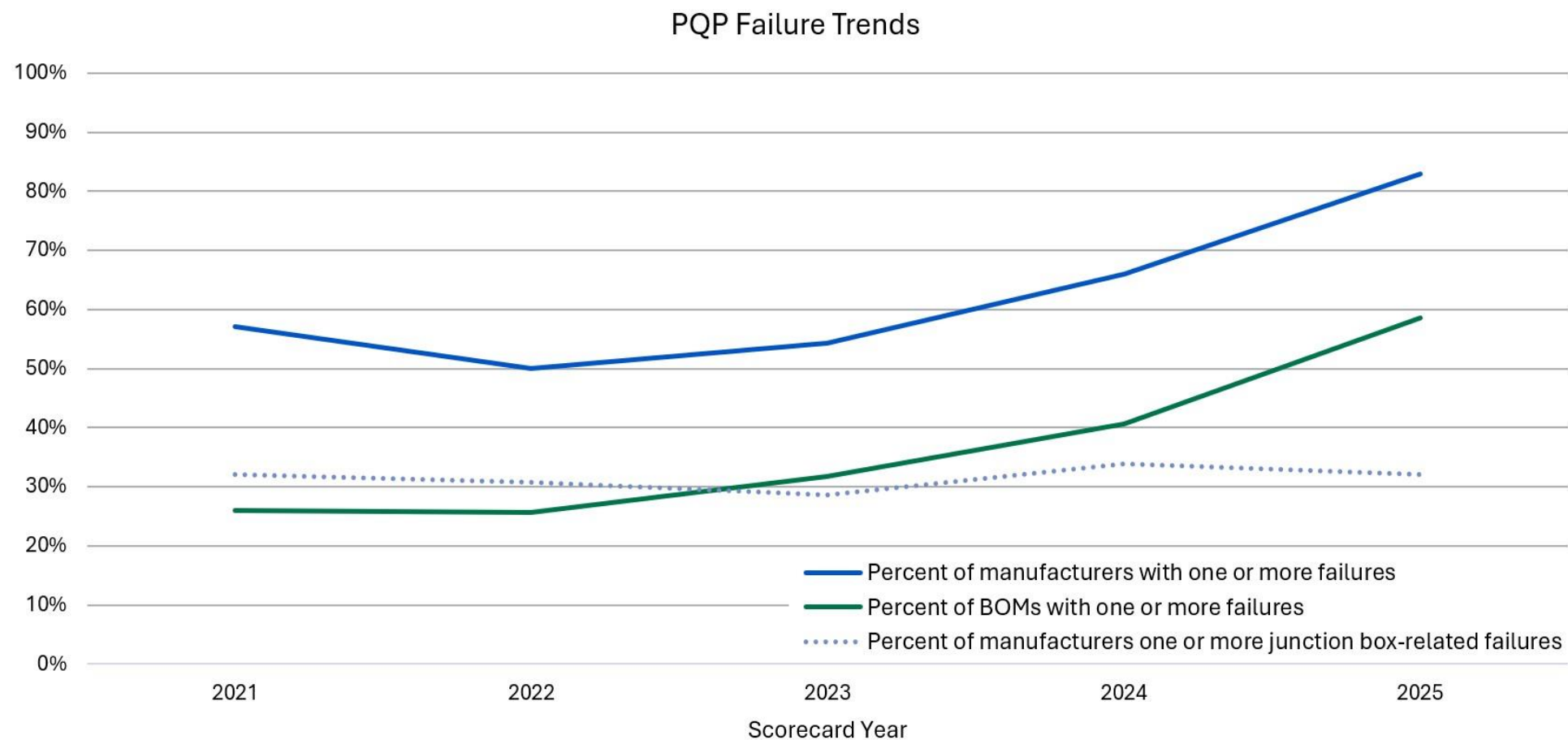
% of PQP Failures per BOM by Test



Initial failures detected during characterizations prior to stress-testing.

Witness failures occurred when the manufacturer decided not to ship the modules following the PQP sample production factory witness due to a quality issue.

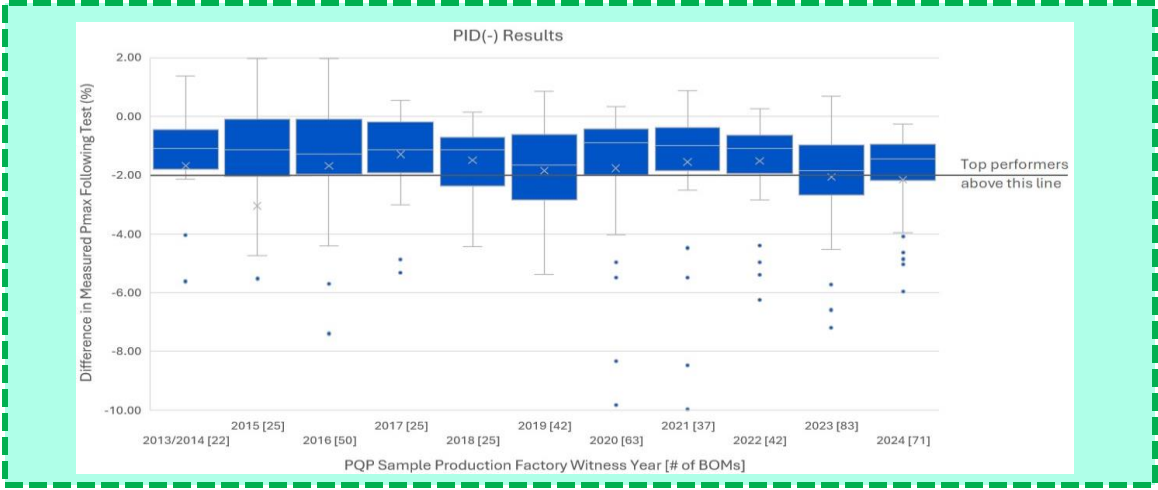
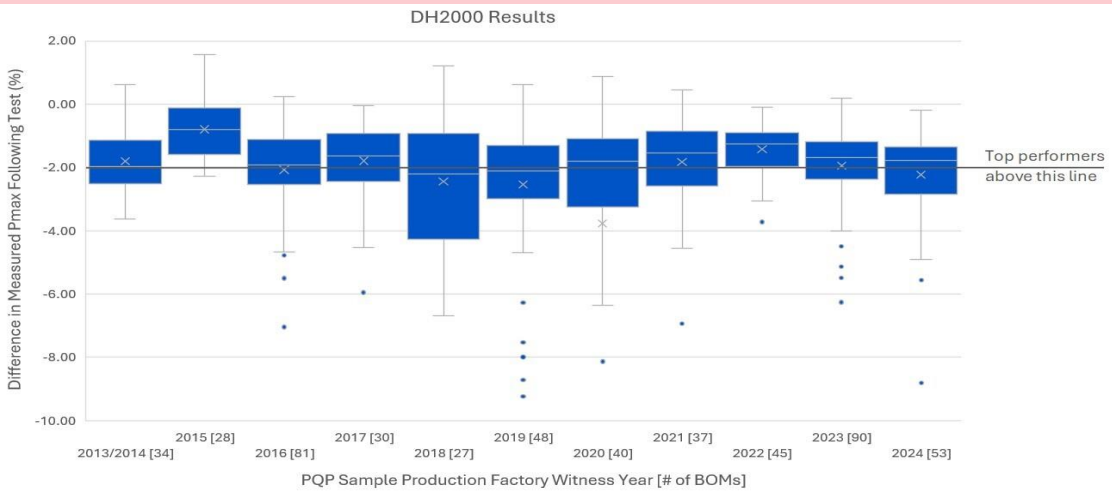
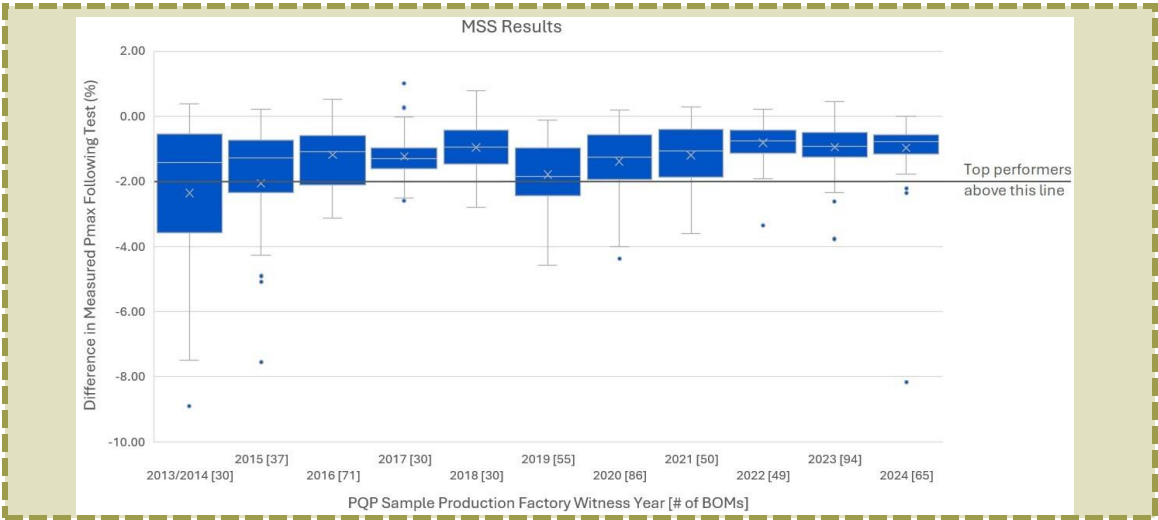
PQP Failure Statistics



Performance Summary

Lower - TC, DH

Minimal - MSS, HSS, LID+LETID





See more of the 2025 Scorecard including all Top Performers at
www.scorecard.pvel.com

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